

SCES088E-OCTOBER 1996-REVISED SEPTEMBER 2004

DGG OR DL PACKAGE

(TOP VIEW)

#### **FEATURES**

- Member of the Texas Instruments Widebus™ Family
- **EPIC™** (Enhanced-Performance Implanted **CMOS) Submicron Process**
- Output Ports Have Equivalent 26- $\Omega$  Series **Resistors, So No External Resistors Are** Required
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per **JESD 17**
- Bus Hold on Data Inputs Eliminates the Need . for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

NOTE: For tape-and-reel order entry, the DGGR package is abbreviated to GR.

### DESCRIPTION

This 20-bit bus-interface D-type latch is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

The SN74ALVCH162841 features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. This device is particularly suitable for implementing buffer registers, unidirectional bus drivers, and working registers.

The SN74ALVCH162841 can be used as two 10-bit latches or one 20-bit latch. The 20-bit latch is a transparent D-type latch. The device has noninverting data (D) inputs and provides true data at its outputs. While the latch-enable (1LE or 2LE) input is high, the Q outputs of the corresponding 10-bit latch follow the D inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable (10E or 20E) input can be used to place the outputs of the corresponding 10-bit latch in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

OE does not affect the internal operation of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The outputs, which are designed to sink up to 12 mA, include equivalent  $26 \Omega$  resistors to reduce overshoot and undershoot.



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1 <del>0E</del>	۵	1	U	56	þ	1LE
1Q1	Π	2		55	þ	1D1
1Q2	C	3		54	þ	1D2
GND	Π	4		53	þ	GND
1Q3	Ц	5		52	þ	1D3
1Q4	Π	6		51	þ	1D4
$V_{CC}$	Π	7		50	þ	V <sub>CC</sub>
1Q5	Π	8		49	þ	1D5
1Q6	Ц	9		48	þ	1D6
1Q7	П	10		47	þ	1D7
GND	Ц	11		46	þ	GND
1Q8	Ц	12		45	þ	1D8
1Q9	Π	13		44	þ	1D9
1Q10	Π	14		43	þ	1D10
2Q1	П	15		42	þ	2D1
2Q2	Π	16		41		2D2
2Q3	Π	17		40	þ	2D3
GND	Π	18		39	þ	GND
2Q4	Ц	19		38	þ	2D4
2Q5	Ц	20		37	β	2D5
2Q6	Ц	21		36	þ	2D6
$V_{CC}$	Ц	22		35	þ	V <sub>CC</sub>
2Q7	Ц	23		34	þ	2D7
2Q8	Ц	24		33	β	2D8
GND	Ц	25		32	β	GND
2Q9	Q	26		31		2D9
2Q10	Q	27		30	μ	2D10
2 <mark>0E</mark>	q	28		29	β	2LE

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### **DESCRIPTION (CONTINUED)**

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating inputs at a valid logic level.

The SN74ALVCH162841 is characterized for operation from -40°C to 85°C.

#### (each 10-bit latch) INPUTS OUTPUT OE LE Q D н L н н L н L L L L Х $Q_0$ н Х Х Ζ

**FUNCTION TABLE** 

	Ľ		•	
10E	1	EN2	7	
1LE	56	C1		
20E	28	EN4		
20E 2LE	29	C3		
ZLE		Ľ°,		
1D1	55	1D 2 \	7 2	1Q1
1D2	54	10 2	3	1Q2
	52		5	
1D3	51		6	1Q3
1D4	49		8	1Q4
1D5	48		9	1Q5
1D6	47		10	1Q6
1D7	45		12	1Q7
1D8	44		13	1Q8
1D9	43		14	1Q9
1D10	42		- 15	1Q10
2D1	41	3D 4 V	7 16	2Q1
2D2	40		10	2Q2
2D3				2Q3
2D4	38		- 19	2Q4
2D5	37		20	2Q5
2D6	36		21	2Q6
2D7	34		23	2Q7
2D8	33		24	2Q8
2D9	31		26	2Q9
2D3	30		27	2Q10
2010				20(10

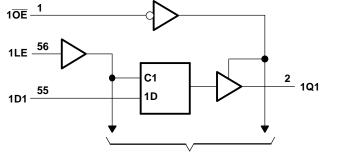
#### LOGIC SYMBOL<sup>(1)</sup>

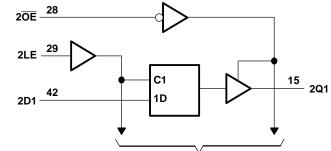
(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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#### LOGIC DIAGRAM (POSITIVE LOGIC)





**To Nine Other Channels** 

To Nine Other Channels

#### ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	4.6	V
VI	Input voltage range <sup>(2)</sup>		-0.5	4.6	V
Vo	Output voltage range <sup>(2)(3)</sup>		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
I <sub>O</sub>	Continuous output current			±50	mA
	Continuous current through each $V_{CC}$ or GN	D		±100	mA
0	$\mathbf{D}_{\mathbf{r}}$ also as the second linear scheme $\mathbf{r}^{(4)}$	DGG package		81	
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DL package		74	°C/W
T <sub>stg</sub>	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) This value is limited to 4.6 V maximum.

(4) The package thermal impedance is calculated in accordance with JESD 51.

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### **RECOMMENDED OPERATING CONDITIONS**<sup>(1)</sup>

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		1.65	3.6	V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65  imes V_{CC}$		
VIH	High-level input voltage	$V_{CC}$ = 2.3 V to 2.7 V	1.7		V
		$V_{CC} = 2.7 V \text{ to } 3.6 V$	2		
		V <sub>CC</sub> = 1.65 V to 1.95 V		$0.35  imes V_{CC}$	
VIL	Low-level input voltage	$V_{CC}$ = 2.3 V to 2.7 V		0.7	V
		$V_{CC} = 2.7 V \text{ to } 3.6 V$		0.8	
VI	Input voltage		0	V <sub>CC</sub>	V
Vo	Output voltage		0	V <sub>CC</sub>	V
		V <sub>CC</sub> = 1.65 V		-2	
		V <sub>CC</sub> = 2.3 V		-6	
I <sub>OH</sub>	High-level output current	$V_{CC} = 2.7 V$		-8	mA
		$V_{CC} = 3 V$		-12	
		V <sub>CC</sub> = 1.65 V		2	
	Low lovel output ourrent	V <sub>CC</sub> = 2.3 V		6	mA
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7 V		8	mA
		$V_{CC} = 3 V$		12	
$\Delta t/\Delta v$	Input transition rise or fall rate	· · · · · · · · · · · · · · · · · · ·		10	ns/V
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

(1) All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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#### **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
		I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			
		I <sub>OH</sub> = -2 mA	1.65 V	1.2			
		$I_{OH} = -4 \text{ mA}$	2.3 V	1.9			V
V <sub>OH</sub>		1 6 mA	2.3 V	1.7			V
		I <sub>OH</sub> = -6 mA	3 V	2.4			
		$I_{OH} = -8 \text{ mA}$	2.7 V	2			
		I <sub>OH</sub> = -12 mA	3 V	2			
		I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.2	
		I <sub>OL</sub> = 2 mA	1.65 V			0.45	
		I <sub>OL</sub> = 4 mA	2.3 V			0.4	
V <sub>OL</sub>			2.3 V			0.55	V
		$I_{OL} = 6 \text{ mA}$	3 V			0.55	
		I <sub>OL</sub> = 8 mA	2.7 V			0.6	
		I <sub>OL</sub> = 12 mA	3 V			0.8	
I <sub>I</sub>		$V_{I} = V_{CC} \text{ or } GND$	3.6 V			±5	μΑ
		V <sub>1</sub> = 0.58 V	1.65 V	25			
		V <sub>1</sub> = 1.07 V	1.65 V	-25			
		V <sub>1</sub> = 0.7 V	2.3 V	45			
I <sub>I(hold)</sub>		V <sub>1</sub> = 1.7 V	2.3 V	-45			μA
. ,		V <sub>1</sub> = 0.8 V	3 V	75			
		V <sub>1</sub> = 2 V	3 V	-75			
		$V_1 = 0$ to 3.6 V <sup>(2)</sup>	3.6 V			±500	
l <sub>oz</sub>		$V_{O} = V_{CC}$ or GND	3.6 V			±10	μΑ
I <sub>CC</sub>		$V_{I} = V_{CC}$ or GND, $I_{O} = 0$	3.6 V			40	μΑ
$\Delta I_{CC}$		One input at $V_{CC}$ - 0.6 V, Other inputs at $V_{CC}$ or GND	3 V to 3.6 V			750	μΑ
	Control inputs		221		4.5		- <b>F</b>
Ci	Data inputs	$V_{I} = V_{CC} \text{ or } GND$	3.3 V		6.5		pF
Co	Outputs	$V_{O} = V_{CC}$ or GND	3.3 V		7		pF
		1	1				

(1)

All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to (2) another.

#### TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

		V <sub>CC</sub> =	1.8 V	V <sub>CC</sub> = ± 0.	2.5 V 2 V	V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = ± 0.	3.3 V 3 V	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
tw	Pulse duration, LE high or low	(1)		3.3		3.3		3.3		ns
t <sub>su</sub>	Setup time, data before LE↑	(1)		0.9		0.7		1.1		ns
t <sub>h</sub>	Hold time, data after LE↑	(1)		1.2		1.5		1.1		ns

(1) This information was not available at the time of publication.

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#### SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER		TO (OUTPUT)	V <sub>CC</sub> = 1.8 V	$\begin{array}{c} \mathrm{V_{CC}=2.5~V}\\ \pm~0.2~\mathrm{V} \end{array}$		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = ± 0.	3.3 V 3 V	UNIT
	(INPUT)	(001-01)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
	D	0	(1)	1	5.3		5.2	1.2	4.3	~~
۲pd	LE	Q	(1)	1	5.9		5.6	1	4.7	ns
t <sub>en</sub>	ŌĒ	Q	(1)	1	6.5		6.5	1	5.3	ns
t <sub>dis</sub>	ŌĒ	Q	(1)	1.1	5.6		4.9	1.3	4.4	ns

(1) This information was not available at the time of publication.

### **OPERATING CHARACTERISTICS**

 $T_A = 25^{\circ}C$ 

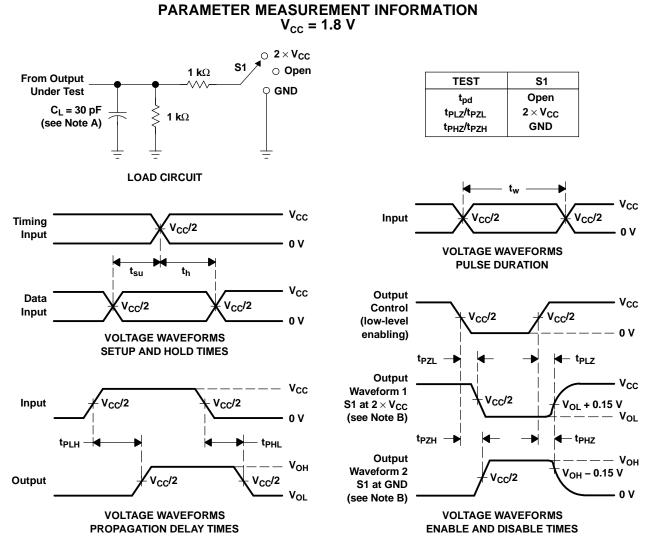
	PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	$V_{CC} = 2.5 V$	$V_{CC}$ = 3.3 V	UNIT
PARAMETER			TEST CONDITIONS	TYP	TYP	TYP	UNIT
<u> </u>	Power dissipation capacitance	Outputs enabled	C <sub>1</sub> = 0, f = 10 MHz	(1)	24	27	۶Ē
Cpd	Power dissipation capacitance	Outputs disabled	$C_L = 0, T = T0 MHZ$	(1)	2	2	рF

(1) This information was not available at the time of publication.

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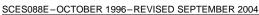
### SN74ALVCH162841 20-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS

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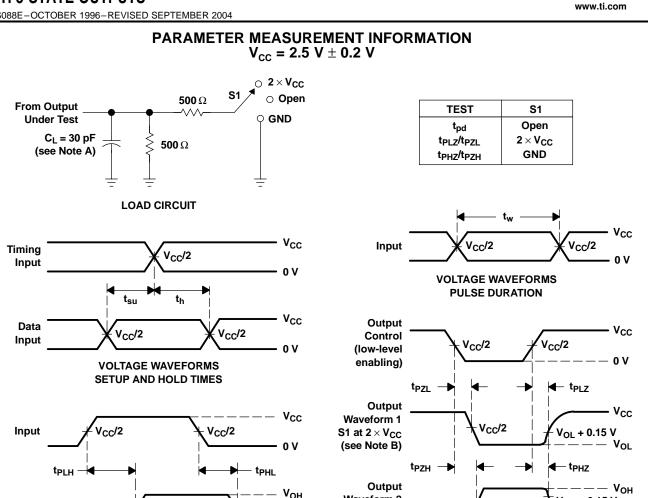


- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

#### Figure 1. Load Circuit and Voltage Waveforms

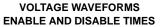






**VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES** 

V<sub>CC</sub>/2



V<sub>CC</sub>/2

V<sub>OH</sub> – 0.15 V

0 V

NOTES: A. C<sub>1</sub> includes probe and jig capacitance.

Output

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

Waveform 2

(see Note B)

S1 at GND

- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.

V<sub>CC</sub>/2

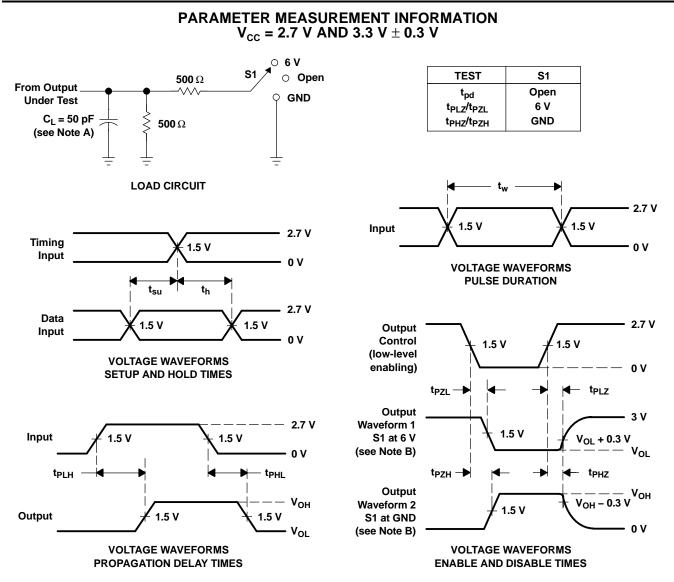
VoL

- E.  $t_{PL7}$  and  $t_{PH7}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

#### Figure 2. Load Circuit and Voltage Waveforms



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NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.

D. The outputs are measured one at a time, with one transition per measurement.

E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .

F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ . G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 3. Load Circuit and Voltage Waveforms



10-Dec-2020

### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALVCH162841DL	ACTIVE	SSOP	DL	56	20	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH162841	Samples
SN74ALVCH162841GR	ACTIVE	TSSOP	DGG	56	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH162841	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## PACKAGE OPTION ADDENDUM

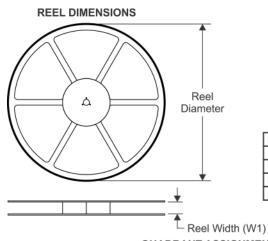
10-Dec-2020

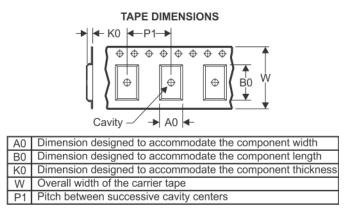
## PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	
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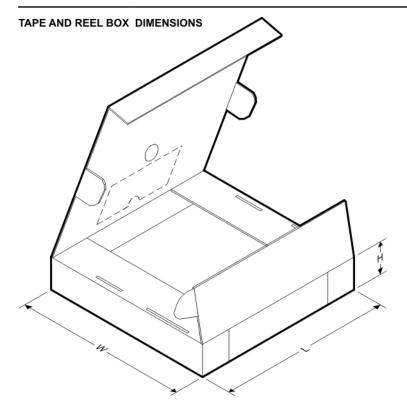
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH162841GR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1



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## PACKAGE MATERIALS INFORMATION

5-Jan-2022



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH162841GR	TSSOP	DGG	56	2000	367.0	367.0	45.0



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5-Jan-2022

### TUBE

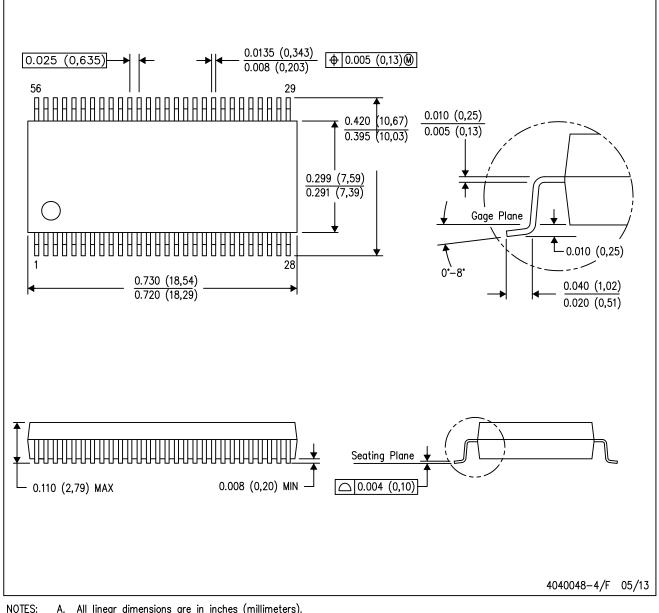


#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN74ALVCH162841DL	DL	SSOP	56	20	473.7	14.24	5110	7.87

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice. В.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15). C.
  - D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.

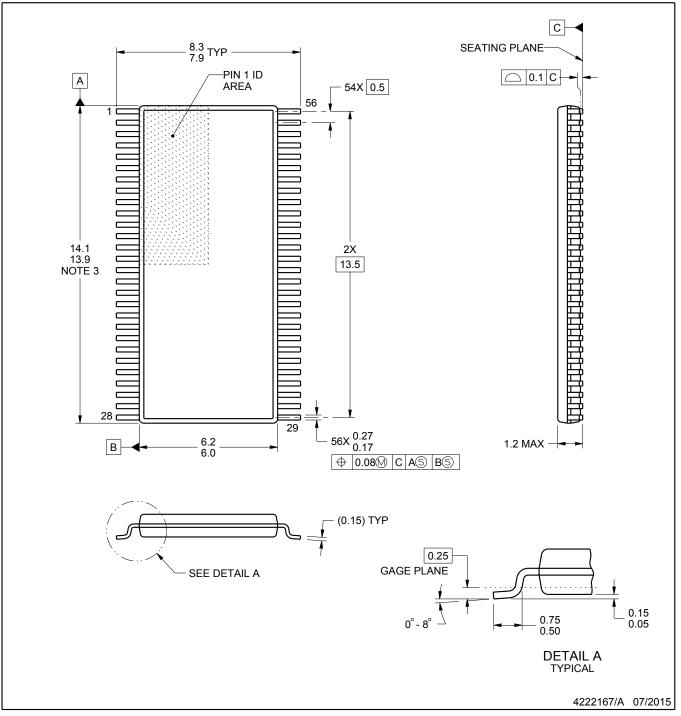


## **PACKAGE OUTLINE**

# **DGG0056A**

### TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not

- exceed 0.15 mm per side. 4. Reference JEDEC registration MO-153.

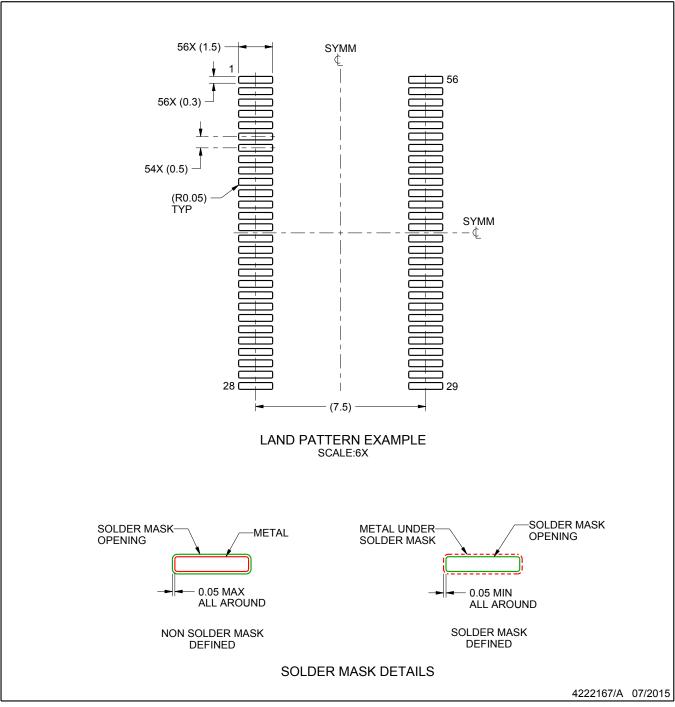


## DGG0056A

## **EXAMPLE BOARD LAYOUT**

## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

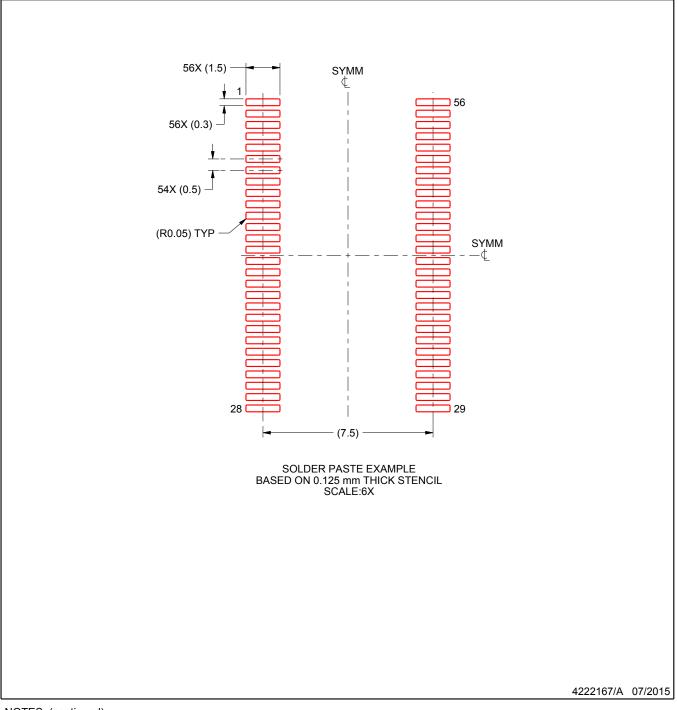


## DGG0056A

## **EXAMPLE STENCIL DESIGN**

### TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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